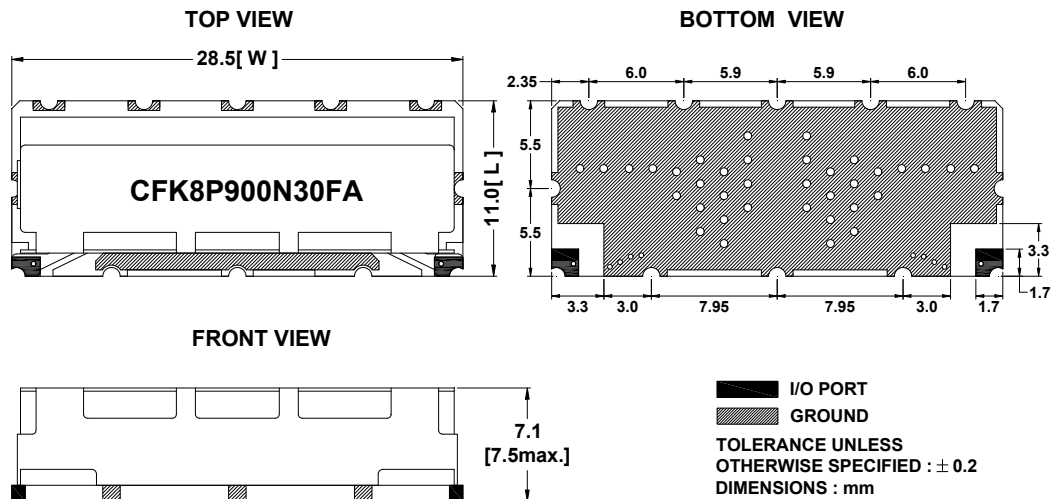


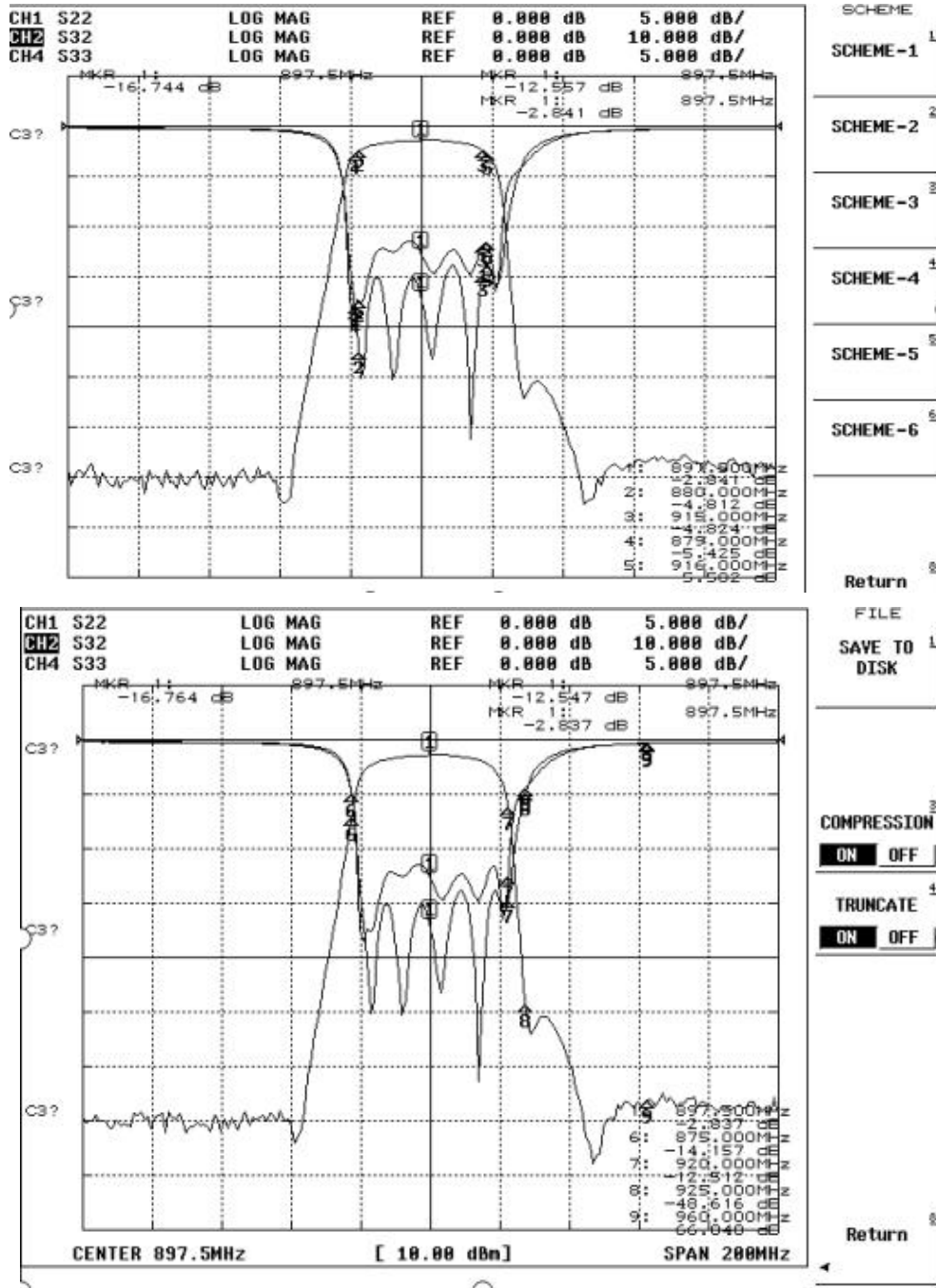
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	897.5	MHz
Bandwidth [BW]	$fo \pm 17.5$ [880.0 ~915.0]	MHz
Insertion Loss in BW	10.0	dB max
Ripple in BW	2.3	dB max
Return Loss in BW	10.0	dB min
Attenuation <input type="checkbox"/> Absolute Value <input checked="" type="checkbox"/> Relative Value	2.5 dBc min. @ $fo \pm 18.5$ [879.0 & 916.0]	MHz
	5.0 dBc min. @ $fo \pm 22.5$ [875.0 &920.0]	MHz
	45.0 dBc min. @ $fo \pm$ [925.0 & 960.0]	MHz
	dB min @ $fo \pm$ [~]	MHz
Group Delay Variation		ns max
Input Power		W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

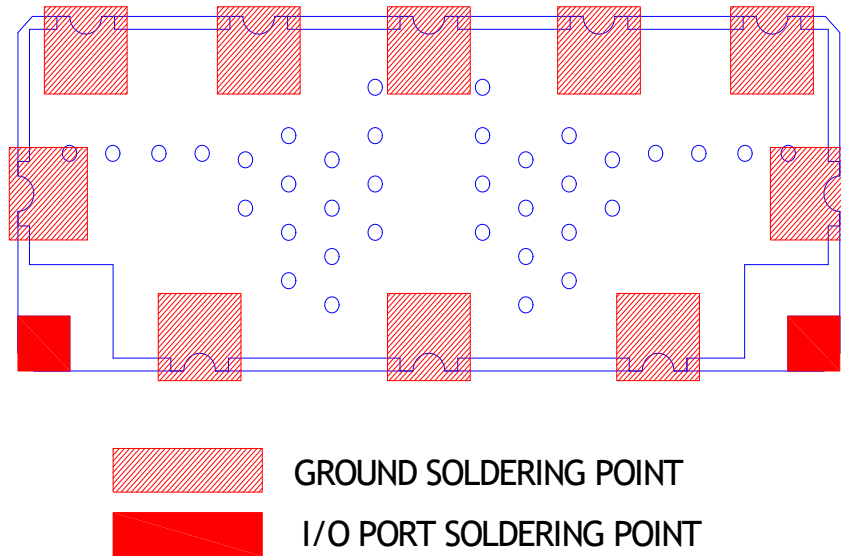
Mechanical Specification



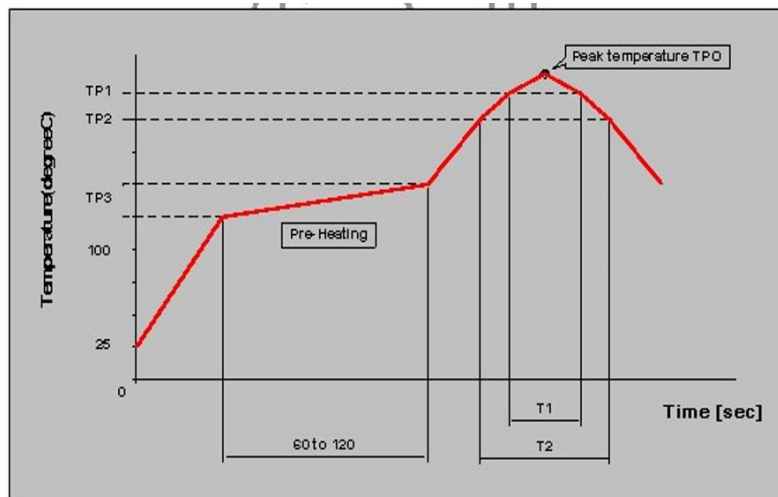
Plot Data



Recommanded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/±0	240	20	220	70	150 to 180